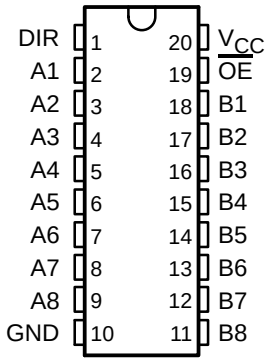
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Reduced Output Structure on A Port Minimizes V_{OHV}**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**

NS PACKAGE
(TOP VIEW)



description/ordering information

This octal bus transceiver is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVTR245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

The A port is designed to minimize the undershoot exhibited on high-to-low transitions during simultaneous switching conditions.

ORDERING INFORMATION

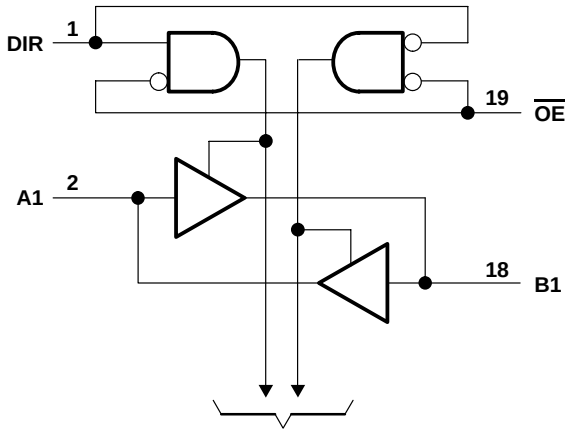
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOP – NS	Tape and reel	SN74LVTR245NSR	LVTR245

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1) . . . . –0.5 V to 7 V
Current into any output in the low state, I_O . . . . . 128 mA
Current into any output in the high state, I_O (see Note 2) . . . . . 64 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Package thermal impedance, θ_{JA} (see Note 3) . . . . . 60°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage			5.5	V
I_{OH}	High-level output current	B port		–32	mA
		A port		–12	
I_{OL}	Low-level output current			32	mA
I_{OL}†	Low-level output current			64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
T_A	Operating free-air temperature		–40	85	°C

† Current duty cycle ≤50%, f ≥ 1 kHz

electrical characteristics over recommended operating free-air temperature range (unlessotherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}	V_{CC} = 2.7 V,	I_I = –18 mA				–1.2	V
V_{OH}	V_{CC} = MIN to MAX‡,	I_{OH} = –100 µA	B port	V_{CC}–0.2			V
	V_{CC} = 2.7 V,	I_{OH} = –8 mA	B port	2.4			
	V_{CC} = 3 V,	I_{OH} = –32 mA	B port	2			
	V_{CC} = MIN to MAX‡,	I_{OH} = –100 µA	A port	V_{CC}–0.2			
	V_{CC} = 2.7 V,	I_{OH} = –1 mA	A port	2.4			
	V_{CC} = 3 V	I_{OH} = –3 mA	A port	2.4			
		I_{OH} = –12 mA	A port	2			
V_{OL}	V_{CC} = 2.7 V	I_{OL} = 100 µA				0.2	V
		I_{OL} = 24 mA				0.5	
	V_{CC} = 3 V	I_{OL} = 16 mA				0.4	
		I_{OL} = 32 mA				0.5	
		I_{OL} = 64 mA				0.55	
I_I	V_{CC} = 3.6 V,	V_I = V_{CC} or GND	Control pins			±1	µA
	V_{CC} = 0 or MAX‡,	V_I = 5.5 V	Control pins			10	
	V_{CC} = 3.6 V	V_I = 5.5 V	A or B ports§			20	
		V_I = V_{CC}	A or B ports§			5	
		V_I = 0	A or B ports§			–5	
$I_{I(hold)}$	V_{CC} = 3 V	V_I = 0.8 V	A or B ports	75			µA
		V_I = 2 V	A or B ports	–75			
I_{OZH}	V_{CC} = 3.6 V,	V_O = 3 V				1	µA
I_{OZL}	V_{CC} = 3.6 V,	V_O = 0.5 V				–1	µA
I_{CC}	V_{CC} = 3.6 V V_I = V_{CC} or GND	I_O = 0,	Outputs high		0.13	0.19	mA
			Outputs low		8.8	12	
			Outputs disabled		0.13	0.19	
ΔI_{CC}¶	V_{CC} = 3 V to 3.6 V,	One input at V_{CC} – 0.6 V,	Other inputs at V_{CC} or GND			0.2	mA
C_i	V_I = 3 V or 0				4		pF
C_{io}	V_O = 3 V or 0				10		pF

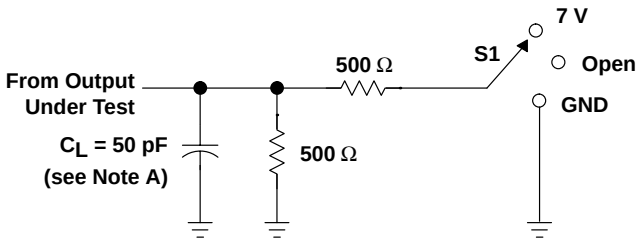
† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
§ Unused pins at V_{CC} or GND
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

switching characteristics, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V ± 0.3 V			V_{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
t_{PLH}	A	B	1.1	2.5	4.2		4.7	ns
	B	A	1.4	2.7	4.4		5.3	
t_{PHL}	A	B	1.1	2.6	4.6		5.8	ns
	B	A	1	2.3	4.1		5.1	
t_{PZH}	$\overline{OE}$	B	1.3	3.1	5.5		6.7	ns
		A	1.6	3.6	6		8.3	
t_{PZL}	$\overline{OE}$	B	2	3.9	6.6		8	ns
		A	1.8	3.8	6.4		7.6	
t_{PHZ}	$\overline{OE}$	B	2.7	4.2	6.1		6.7	ns
		A	2.5	4	5.8		6.4	
t_{PLZ}	$\overline{OE}$	B	2.4	3.7	5.2		5.4	ns
		A	2.4	3.7	5.2		5.3	

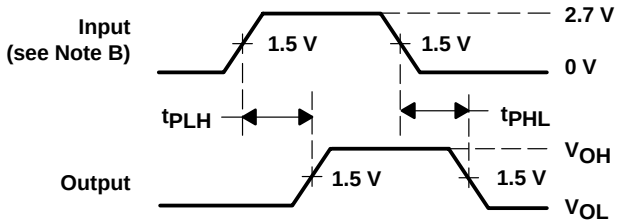
† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

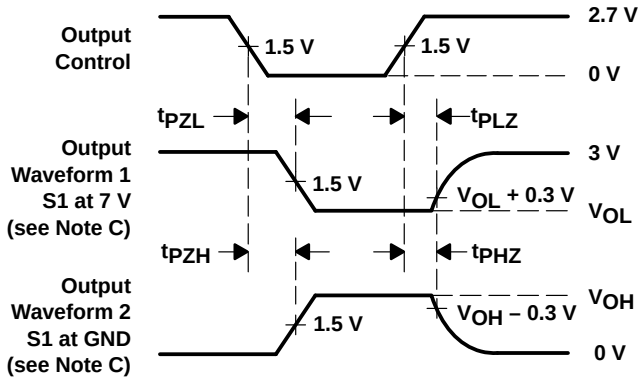


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT FOR OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LVTR245NSR	OBSOLETE	SO	NS	20		TBD	Call TI	Call TI	-40 to 85		
SN74LVTR245PW	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		
SN74LVTR245PWR	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		

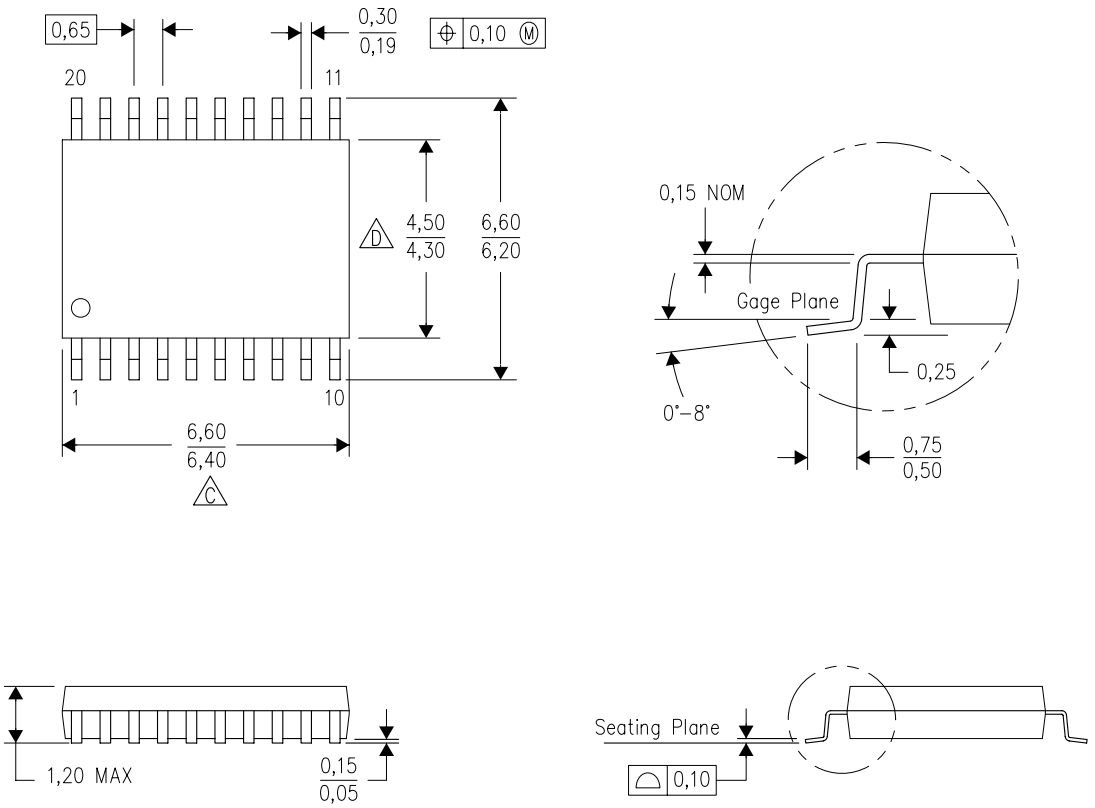
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

PW (R–PDSO–G20) PLASTIC SMALL OUTLINE



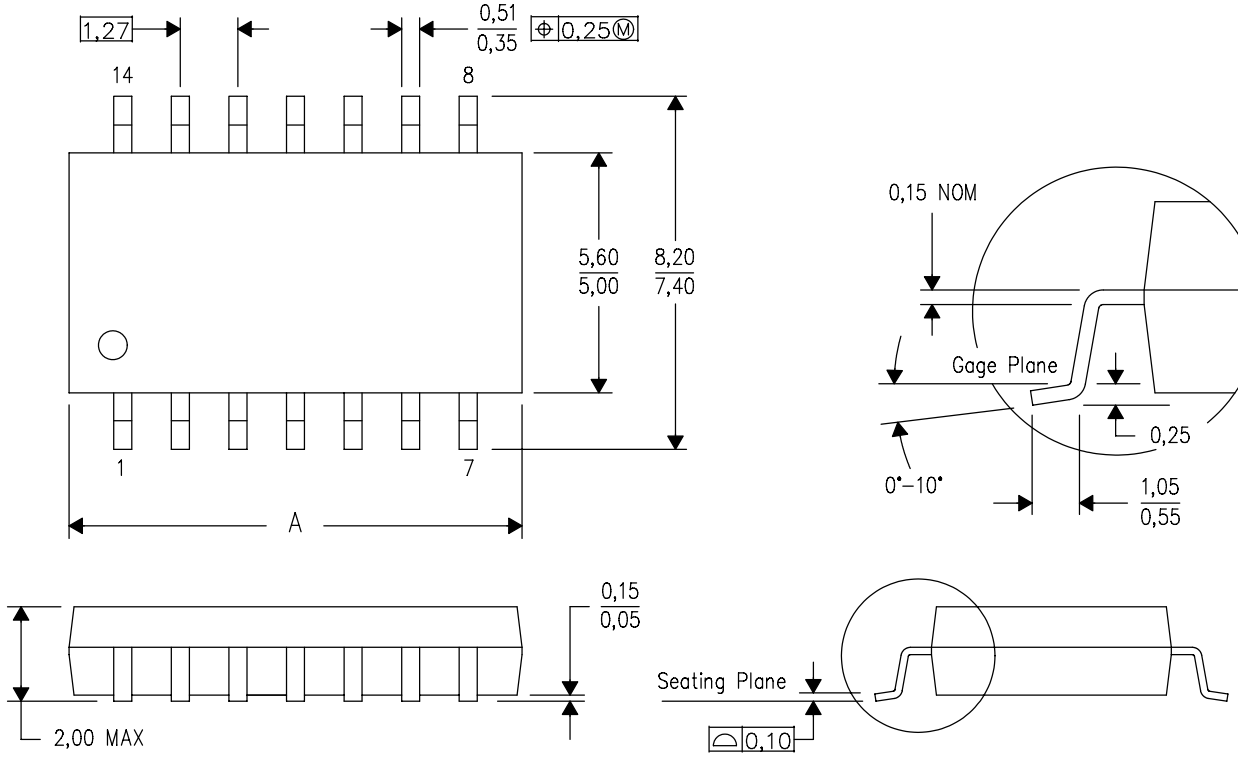
4040064–5/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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